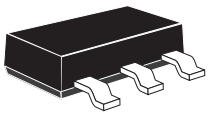
ZXMN6A11G

60V N-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY
$V_{(BR)DSS}$= 60V; $R_{DS(ON)}$= 0.14Ω I_D= 3.8A

DESCRIPTION

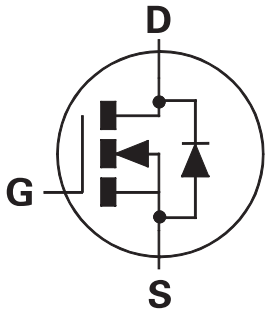
This new generation of TRENCH MOSFETs from Zetex utilises a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



SOT223

FEATURES

- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- SOT223 package

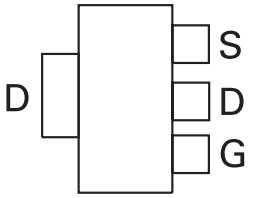


APPLICATIONS

- DC - DC Converters
- Power Management Functions
- Relay and Solenoid driving
- Motor control

ORDERING INFORMATION

DEVICE	REEL SIZE	TAPE WIDTH	QUANTITY PER REEL
ZXMN6A11GFTA	7″	12mm	1000 units
ZXMN6A11GFTC	13″	12mm	4000 units



Top View

DEVICE MARKING

- ZXMN
  6A11

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current V_{GS}=10V; T_A=25°C(b) V_{GS}=10V; T_A=70°C(b) V_{GS}=10V; T_A=25°C(a)	I_D	3.8 3.0 2.7	A
Pulsed Drain Current (c)	I_{DM}	10	A
Continuous Source Current (Body Diode) (b)	I_S	5	A
Pulsed Source Current (Body Diode)(c)	I_{SM}	10	A
Power Dissipation at T_A=25°C (a) Linear Derating Factor	P_D	2.0 16	W mW/°C
Power Dissipation at T_A=25°C (b) Linear Derating Factor	P_D	3.9 31	W mW/°C
Operating and Storage Temperature Range	T_j:T_{stg}	-55 to +150	°C

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	62.5	°C/W
Junction to Ambient (b)	$R_{\theta JA}$	32	°C/W

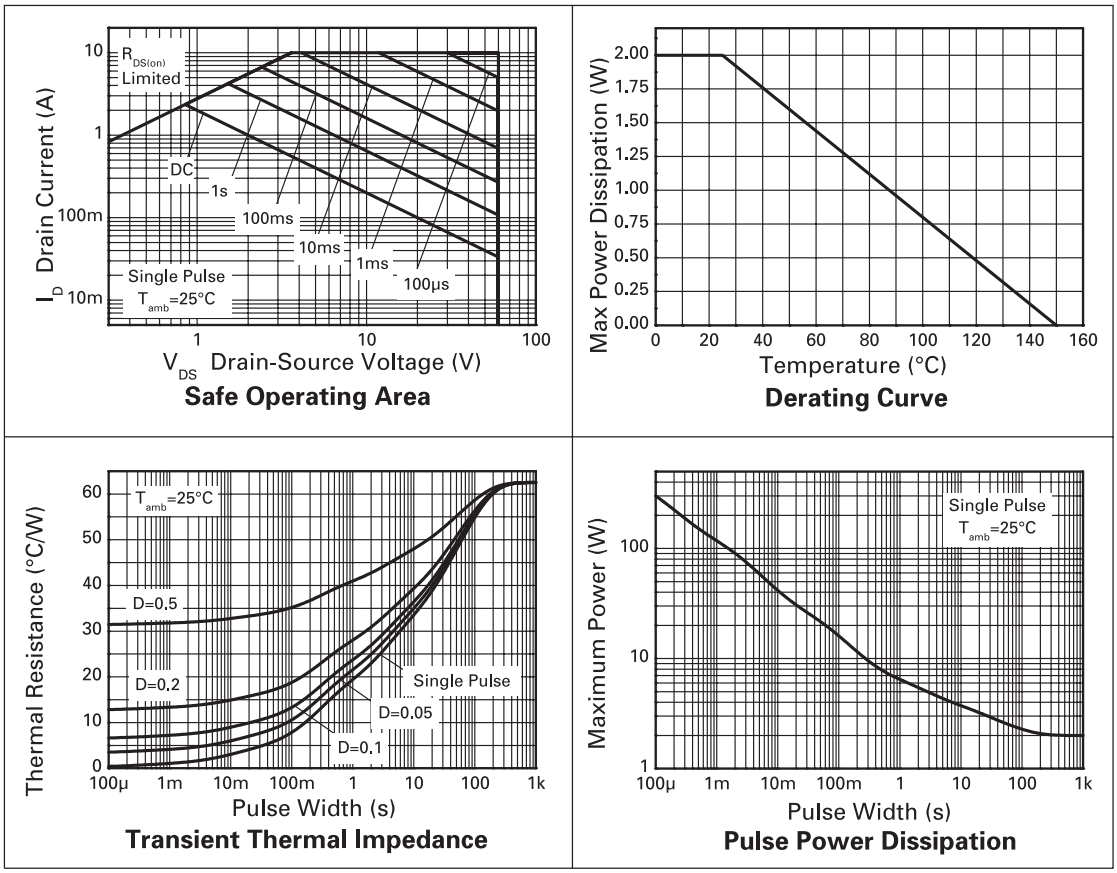
NOTES

(a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions

(b) For a device surface mounted on FR4 PCB measured at t≤5 secs.

(c) Repetitive rating 25mm x 25mm FRA PCB, D=0.05 pulse width = 10μs - pulse width limited by maximum junction temperature.

CHARACTERISTICS



ELECTRICAL CHARACTERISTICS (at TA = 25°C unless otherwise stated)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	60			V	I_D=250μA, V_{GS}=0V
Zero Gate Voltage Drain Current	I_{DSS}			1	μA	V_{DS}=60V, V_{GS}=0V
Gate-Body Leakage	I_{GSS}			100	nA	V_{GS}=±20V, V_{DS}=0V
Gate-Source Threshold Voltage	$V_{GS(th)}$	1.0			V	I_D=250μA, V_{DS}= V_{GS}
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.140 0.250	Ω Ω	V_{GS}=10V, I_D=4.4A V_{GS}=4.5V, I_D=3.8A
Forward Transconductance (3)	g_{fs}		4.9		S	V_{DS}=15V,I_D=2.5A
DYNAMIC (3)						
Input Capacitance	C_{iss}		330		pF	V_{DS}=40 V, V_{GS}=0V, f=1MHz
Output Capacitance	C_{oss}		35.2		pF	
Reverse Transfer Capacitance	C_{rss}		17.1		pF	
SWITCHING(2) (3)						
Turn-On Delay Time	$t_{d(on)}$		1.95		ns	V_{DD} =30V, I_D=2.5A R_G=6.0Ω, V_{GS}=10V (refer to test circuit)
Rise Time	t_r		3.5		ns	
Turn-Off Delay Time	$t_{d(off)}$		8.2		ns	
Fall Time	t_f		4.6		ns	
Gate Charge	Q_g		3.0		nC	V_{DS}=15V, V_{GS}=5V, I_D=2.5A
Total Gate Charge	Q_g		5.7		nC	V_{DS}=15V,V_{GS}=10V, I_D=2.5A (refer to test circuit)
Gate-Source Charge	Q_{gs}		1.25		nC	
Gate-Drain Charge	Q_{gd}		0.86		nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}		0.85	0.95	V	T_J=25°C, I_S=2.8A, V_{GS}=0V
Reverse Recovery Time (3)	t_{rr}		21.5		ns	T_J=25°C, I_F=2.5A, di/dt= 100A/μs
Reverse Recovery Charge (3)	Q_{rr}		20.5		nC	

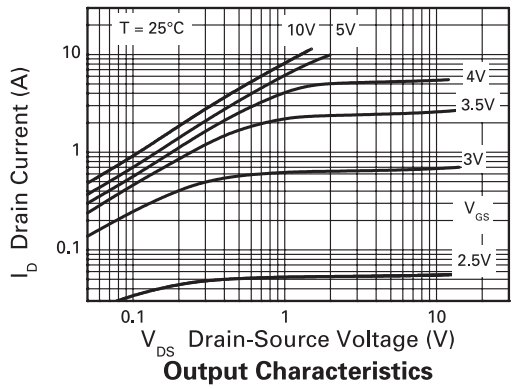
NOTES

(1) Measured under pulsed conditions. Width≤300μs. Duty cycle ≤ 2% .

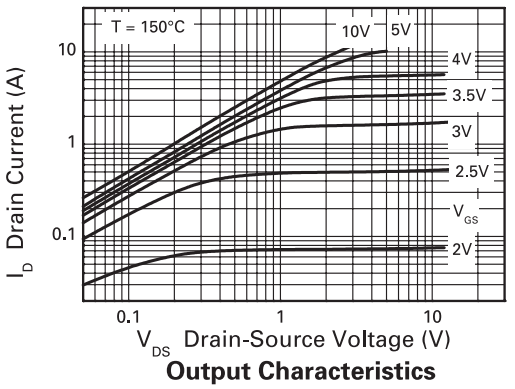
(2) Switching characteristics are independent of operating junction temperature.

(3) For design aid only, not subject to production testing.

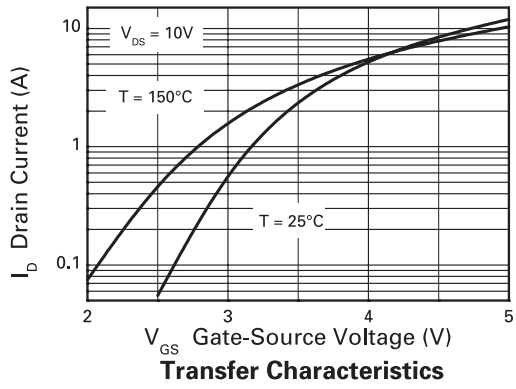
TYPICAL CHARACTERISTICS



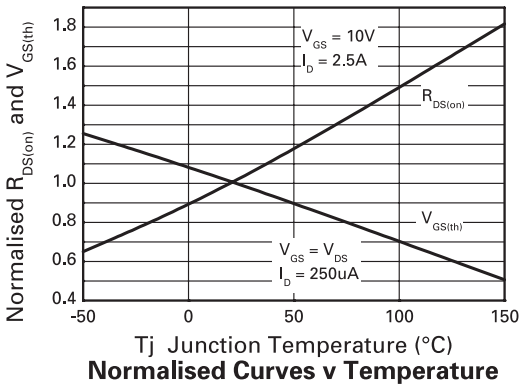
Output Characteristics



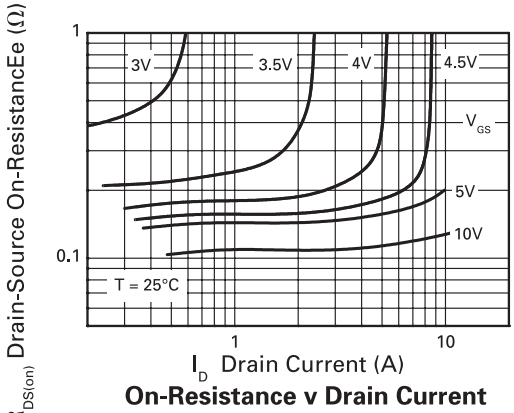
Output Characteristics



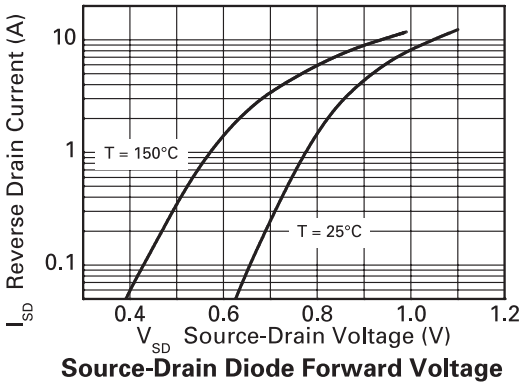
Transfer Characteristics



Normalised Curves v Temperature

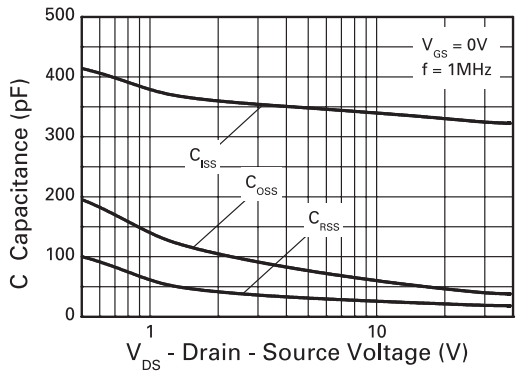


On-Resistance v Drain Current

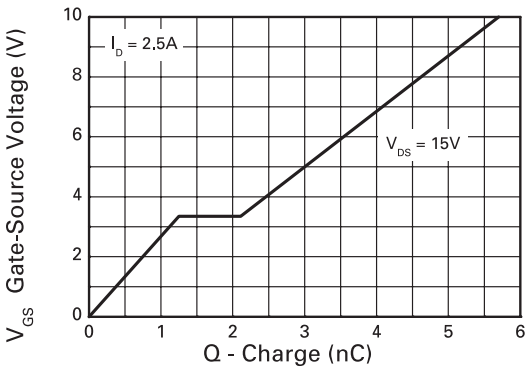


Source-Drain Diode Forward Voltage

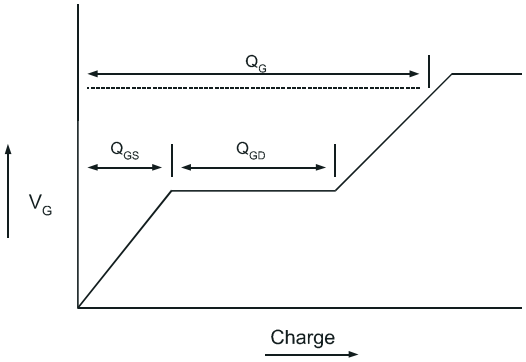
TYPICAL CHARACTERISTICS



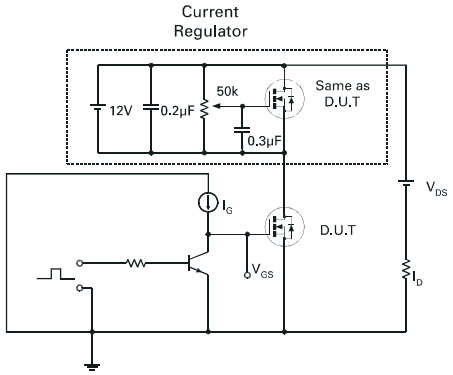
Capacitance v Drain-Source Voltage



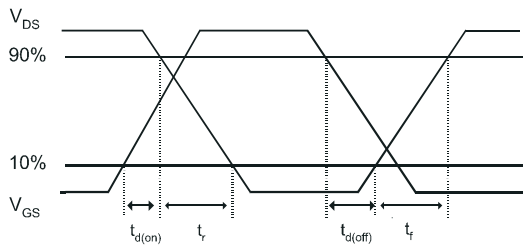
Gate-Source Voltage v Gate Charge



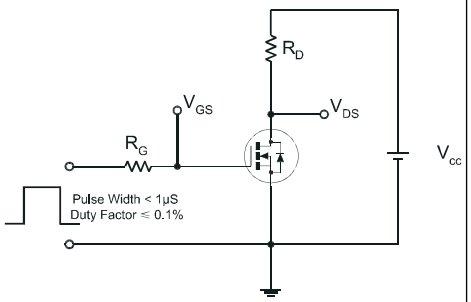
Basic Gate Charge Waveform



Gate Charge Test Circuit

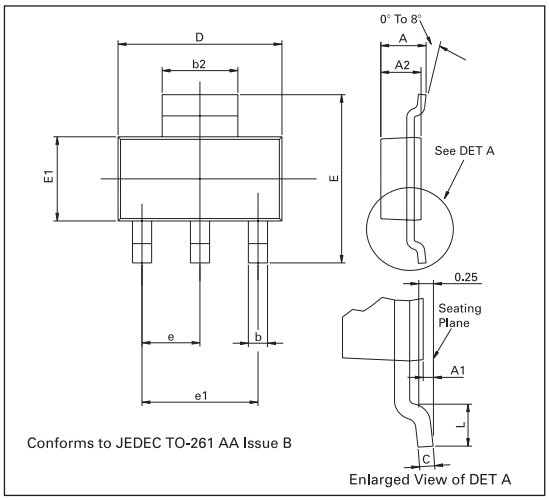


Switching Time Waveforms

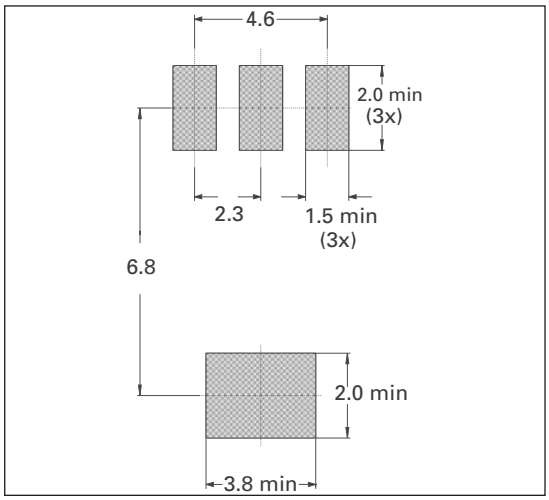


Switching Time Test Circuit

PACKAGE OUTLINE



PAD LAYOUT DETAILS



PACKAGE DIMENSIONS

DIM	MILLIMETRES		DIM	MILLIMETRES	
	MIN	MAX		MIN	MAX
A	—	1.80	D	6.30	6.70
A1	0.02	0.10	e	2.30 BASIC	
A2	1.55	1.65	e1	4.60 BASIC	
b	0.66	0.84	E	6.70	7.30
b2	2.90	3.10	E1	3.30	3.70
C	0.23	0.33	L	0.90	—

Zetex plc
Fields New Road
Chadderton
Oldham, OL9 8NP
United Kingdom
Telephone (44) 161 622 4422
Fax: (44) 161 622 4420

Zetex GmbH
Streitfeldstraße 19
D-81673 München
Germany
Telefon: (49) 89 45 49 49 0
Fax: (49) 89 45 49 49 49

Zetex Inc
700 Veterans Memorial Hwy
Hauppauge, NY11788
USA
Telephone: (631) 360 2222
Fax: (631) 360 8222

Zetex (Asia) Ltd
3701-04 Metroplaza, Tower 1
Hing Fong Road
Kwai Fong
Hong Kong
Telephone: (852) 26100 611
Fax: (852) 24250 494

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